



*Vacuum deposited Copper zinc tin sulfide (CZTS) thin film
solar cells*

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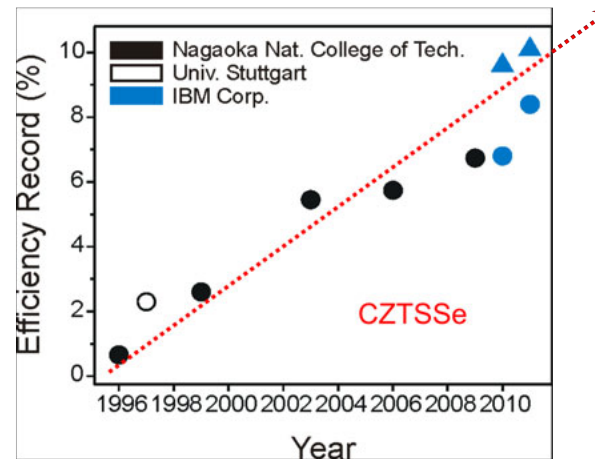
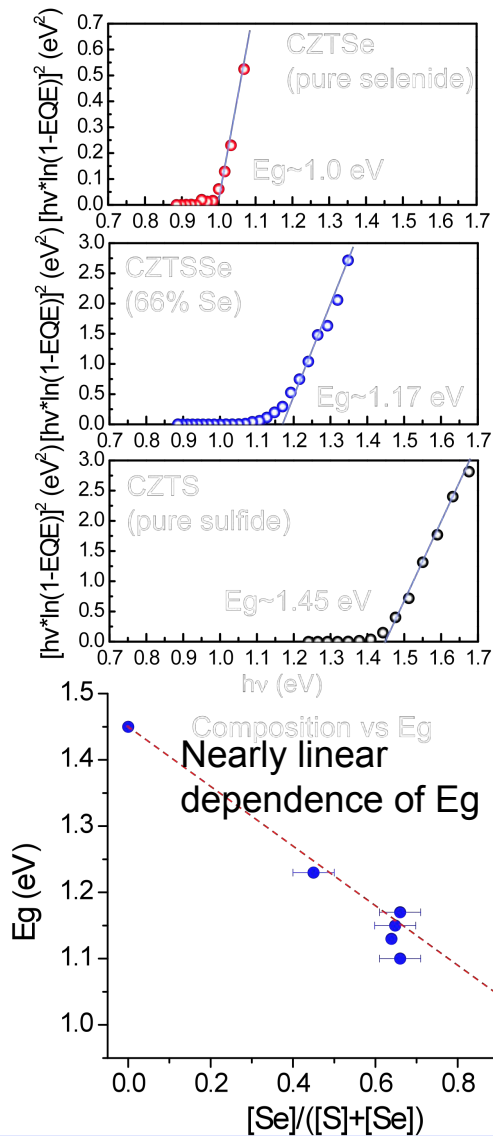
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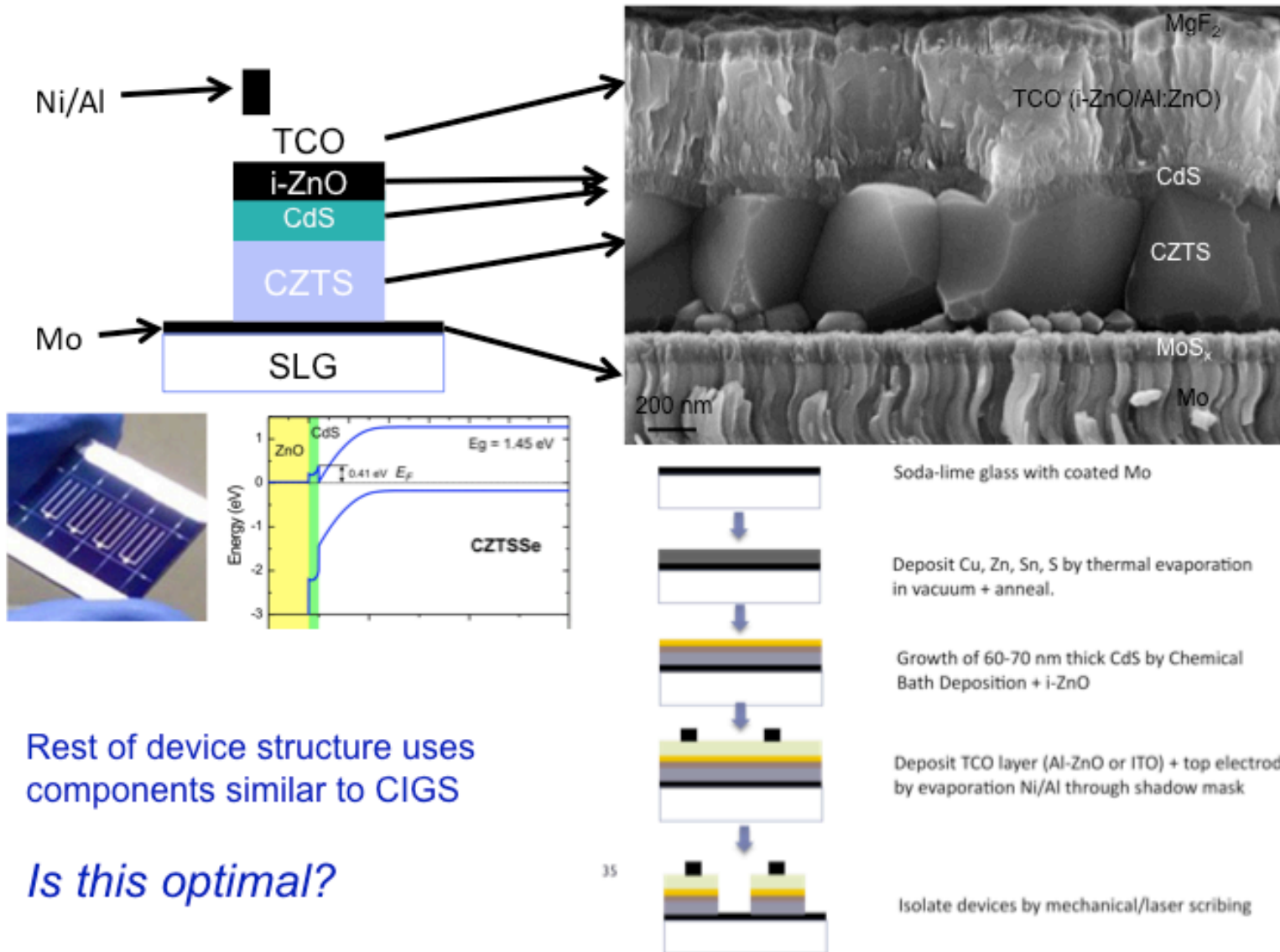
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Tunable band gap of CZTSSe

Only truly earth abundant non-Si absorber with efficiencies >10%



- *Solution processed* \rightarrow highest efficiency, $\sim 11\%$ (CZTSSe)
- *Thermal evaporation* \rightarrow highest efficiency, 8.4% (CZTS), 9.15% (CZTSe)
- *Electroplating* $\rightarrow 7.4\%$ (CZTS)
- *Need* $\rightarrow >15\%$, eventually $>18\%$



Rest of device structure uses components similar to CIGS

Is this optimal?

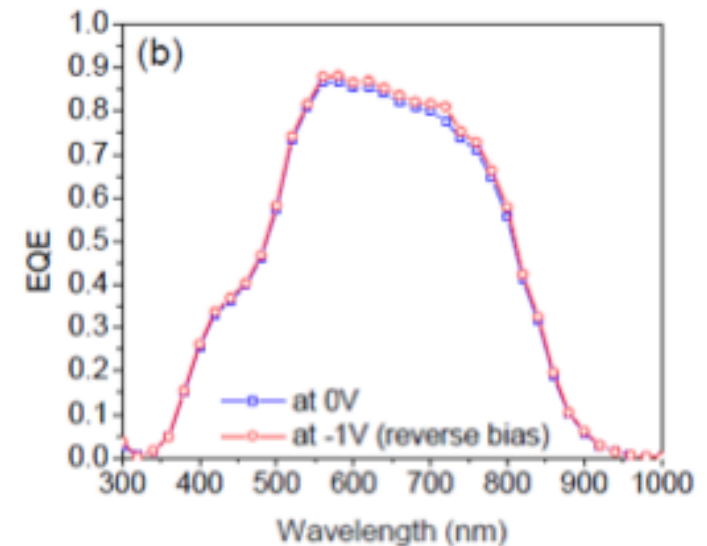
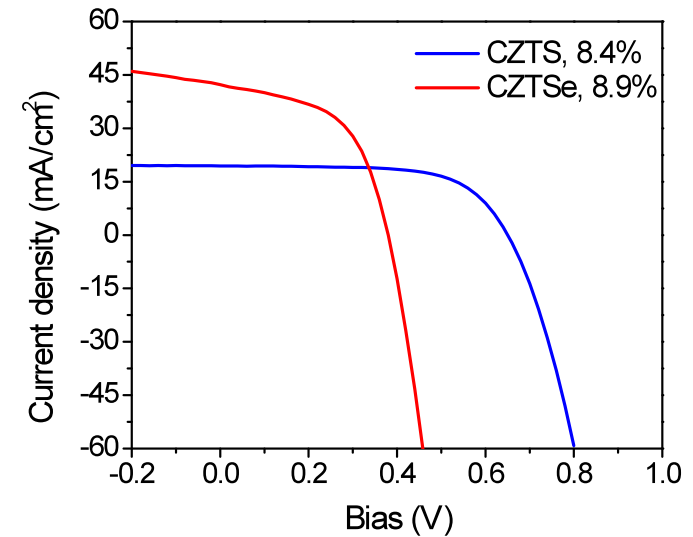
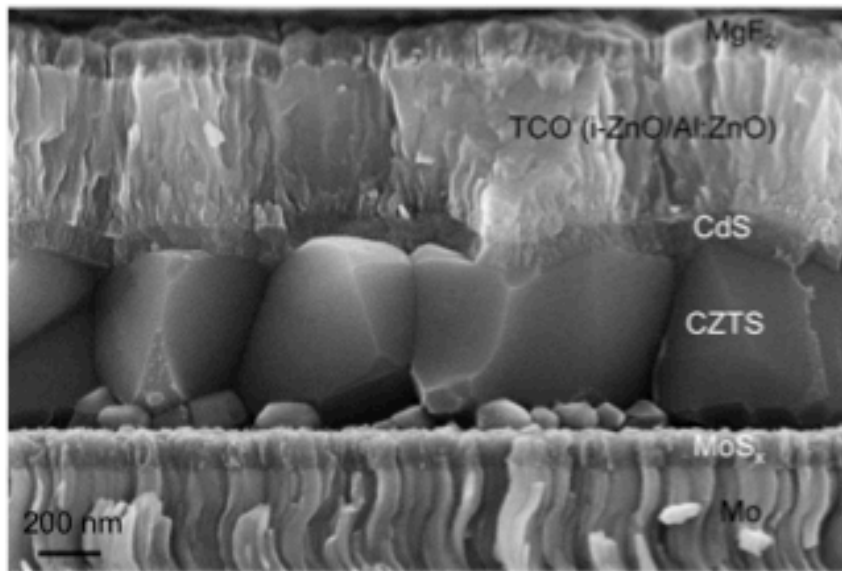
Vacuum deposited CZTS_{Se}

8.4% (FF~65%) Cu₂ZnSnS₄ solar cell

8.9% (FF~54%) Cu₂ZnSnSe₄ solar cell

100% sulfur preferable

Cu:Sn → 1.8-1.9; Zn:Sn → 1.3-1.4

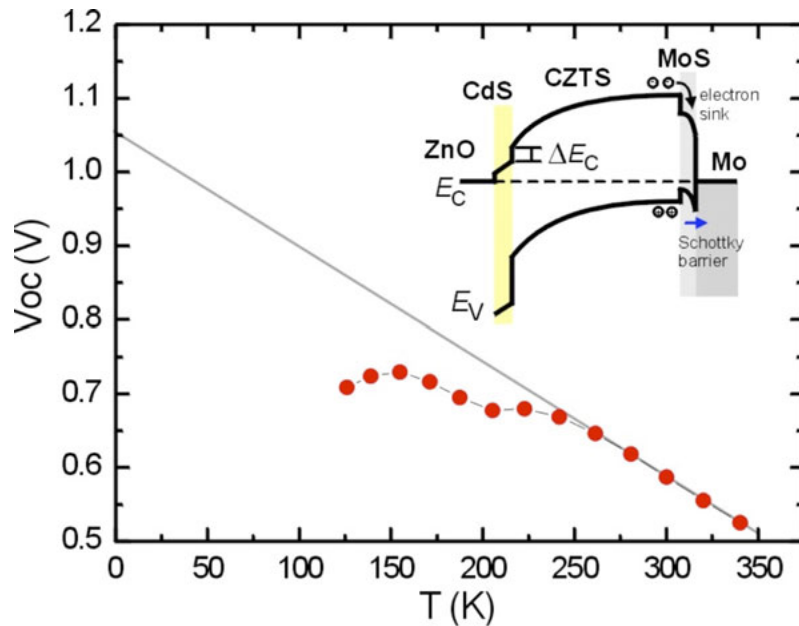


Shin, Zhu, Gunawan, Chey, Bojarczuk, Guha, Prog. Photovolt. DOI: 10.1002/pip.1174

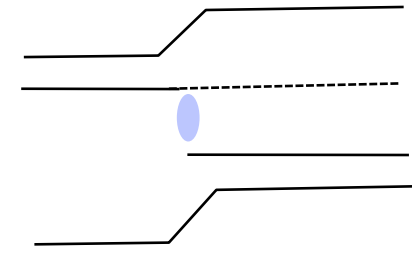
Major problems in CZTS where TSM can help

1) Why is the Voc low?

$$V_{oc} = \frac{E_A}{q} - \frac{AkT}{q} \ln \frac{J_{00}}{J_L}$$



Temperature dependence of the open circuit voltage (V_{oc})

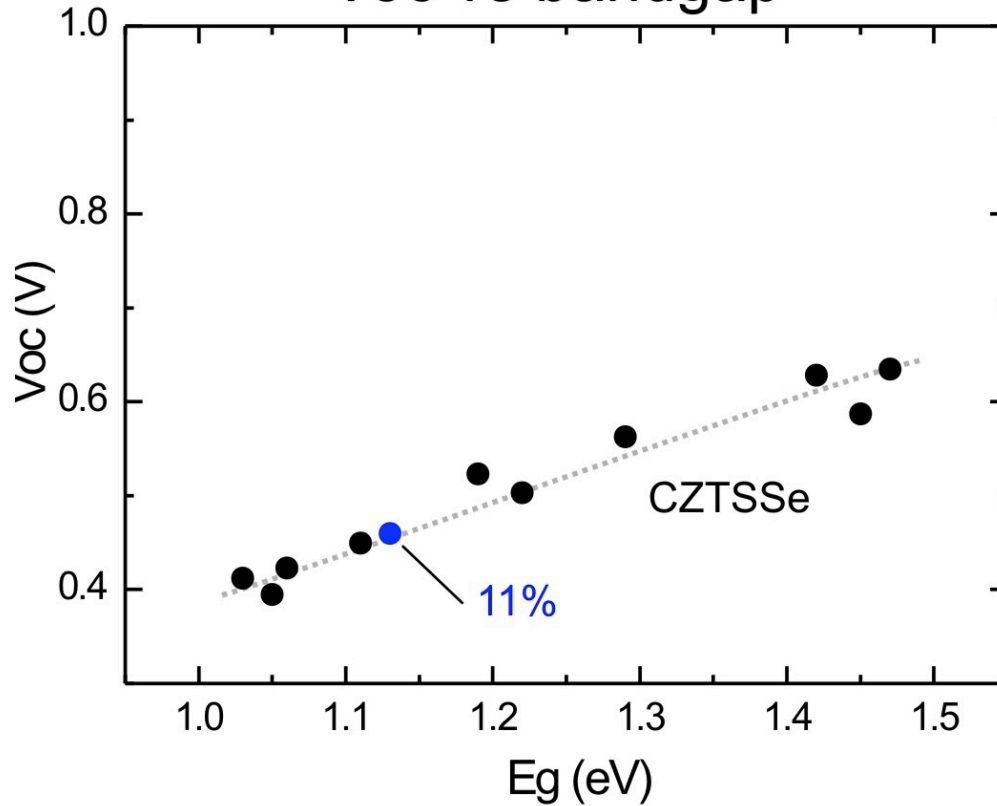


- Dominant carrier recombination mechanism can be obtained from the open circuit voltage vs. temperature data [1]

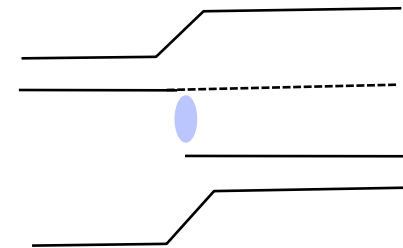
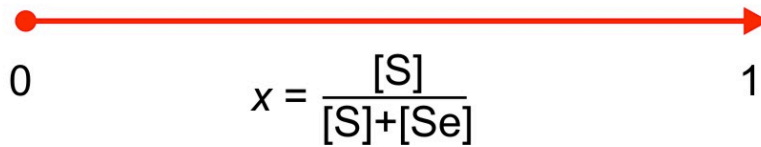
[1] U. Rau, Cu(In,Ga)Se₂ solar cells, Chap. 7 Clean energy from photovoltaics, Imperial College Press, London (2000).

[2] M. Gloeckler, J.R. Sites, Efficiency limitations for wide-bandgap chalcopyrite solar cell, Thin Solid films 4801, 241 (2005).

Voc vs bandgap

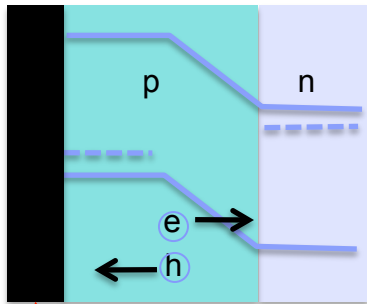


- Low carrier lifetimes—not likely
- Voltage barrier at interface
- Fermi level deep in gap
- Alloy composition fluctuations



From Gunawan and Mitzi

Problem #2: poor carrier lifetimes

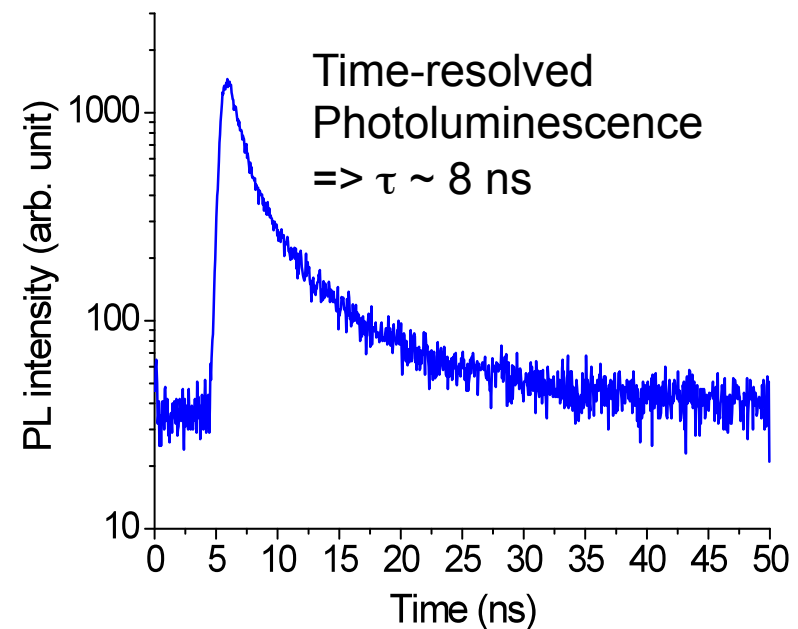


Back contact

Thickness dependent efficiencies

Need an accurate model for the device
Where does recombination occur?

CZTS: J_{sc} typically $\sim 20 \text{ mA/cm}^2$
theoretically \sim low 30s mA/cm^2

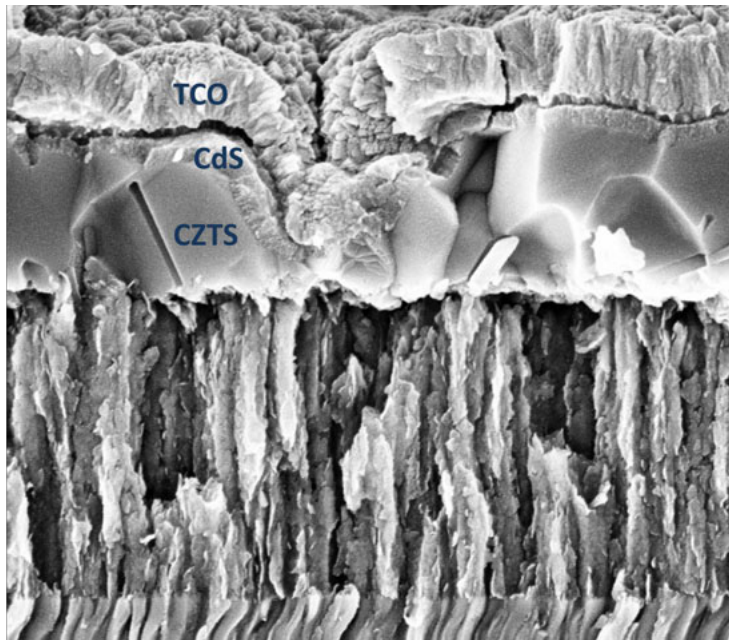
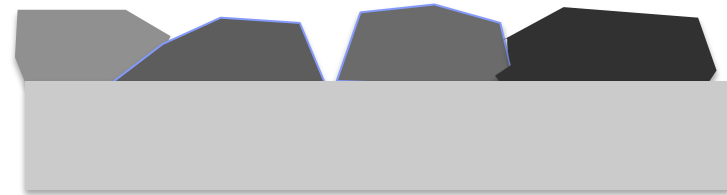


Problem #3: thin film microstructure—grain boundaries

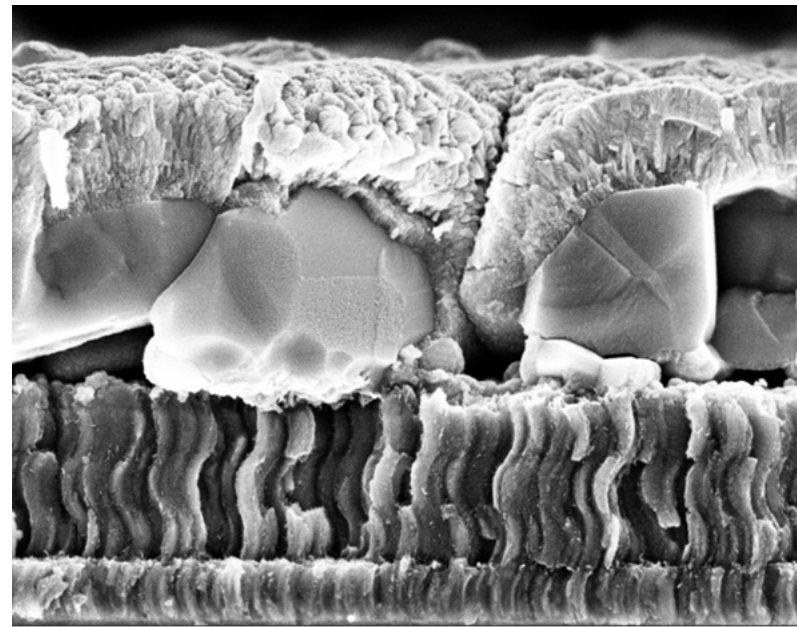
Re-entrant grain boundaries—good or bad?

gb conductivity

gb diffusion



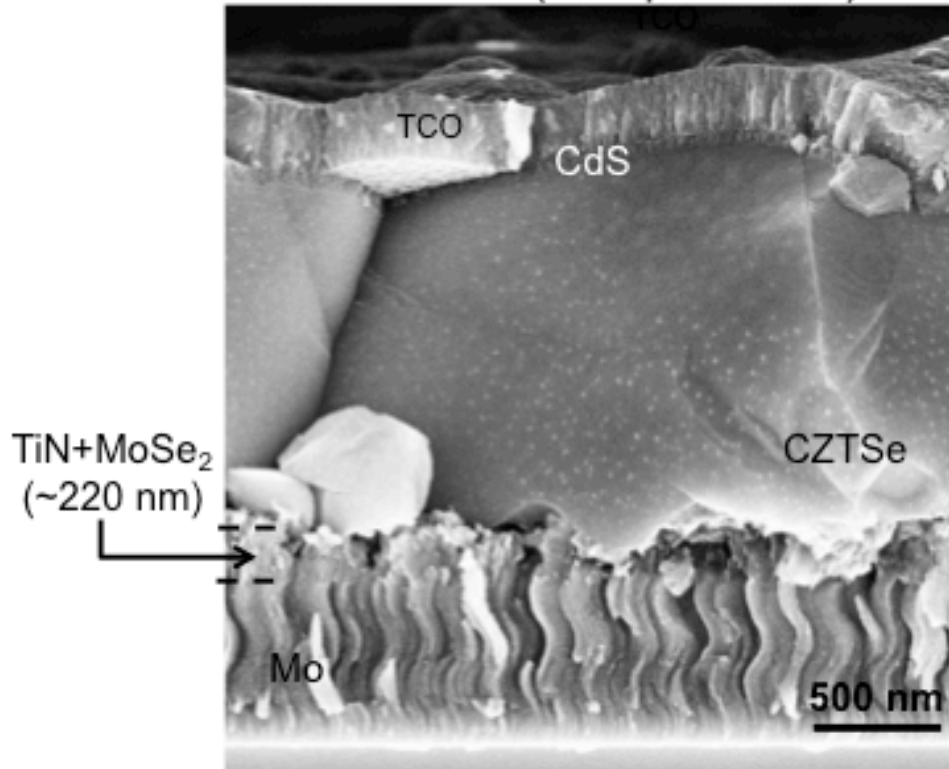
Mag = 35.00 K X | 100 nm | EHT = 5.00 kV | Date :25 Jul 2 |
WD = 3.6 mm | File Name = R50-3_



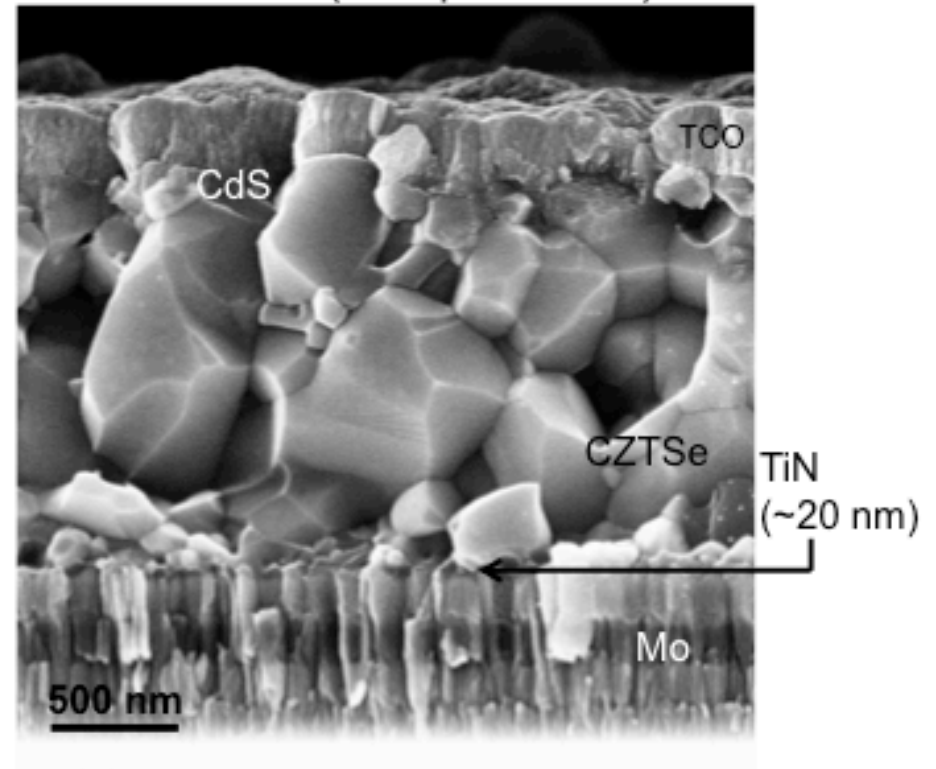
.00 K X | 100 nm | EHT = 5.00 kV | Date :25 Jul 2012 |
WD = 3.2 mm | File Name = R51-3_S1_1.tif

TiN diffusion barrier between CZTSe and Mo: SEM

570°C anneal (Sample #TiN2)



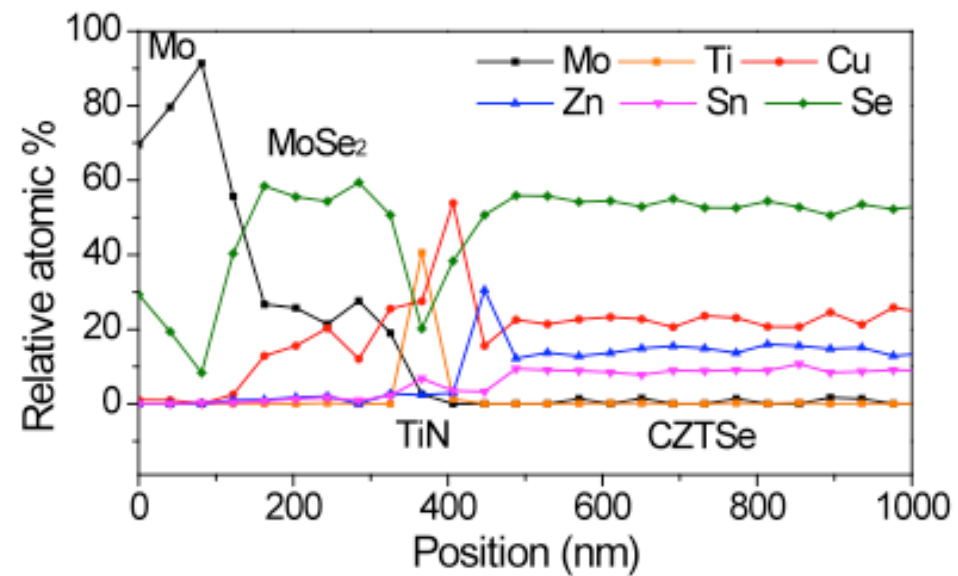
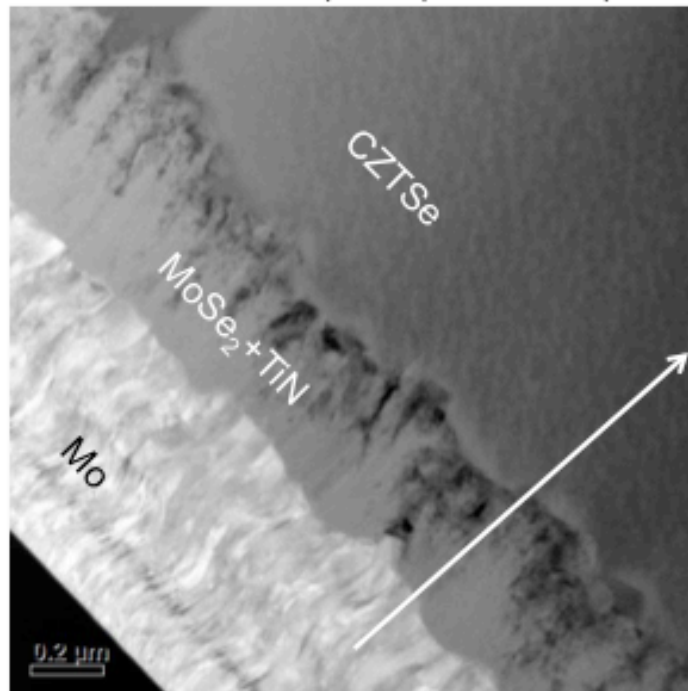
480°C anneal (Sample #TiN1)



- With 20 nm TiN, MoSe₂ formation completely suppressed at 480°C
- At 570°C, MoSe₂ still formed but its thickness (~220 nm) is much smaller without TiN (~1300 nm)

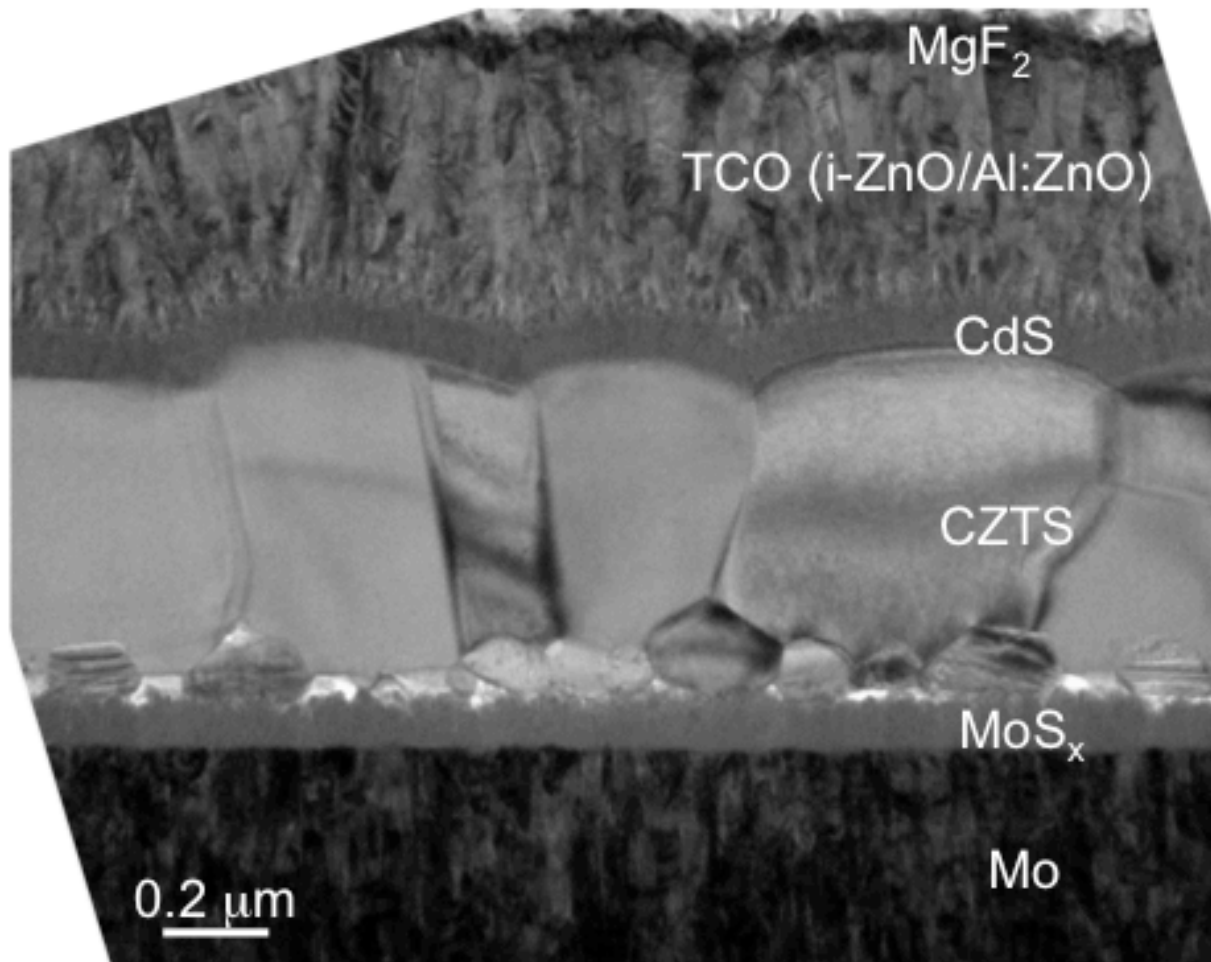
TiN diffusion barrier between CZTSe and Mo: TEM

570°C anneal (Sample #TiN2)

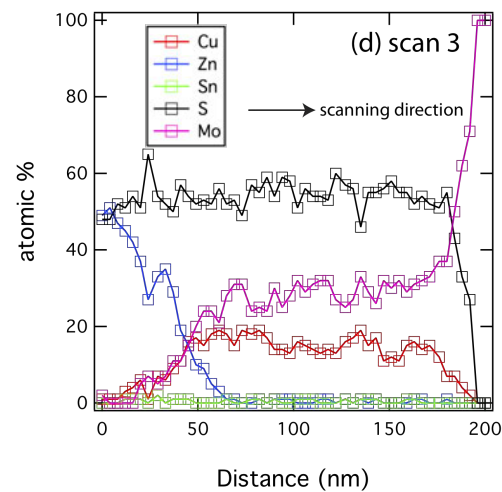
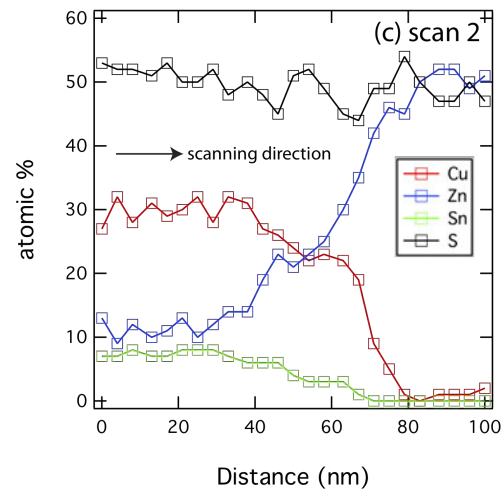
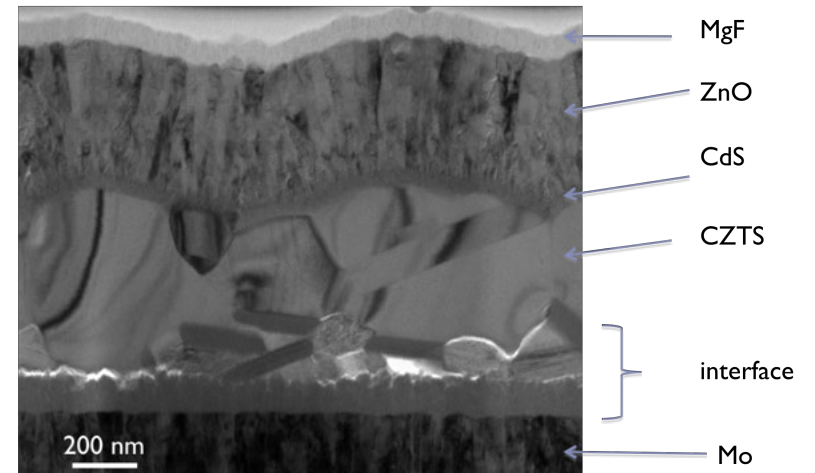
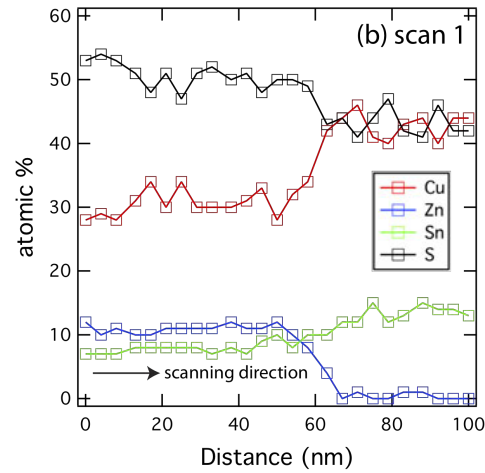
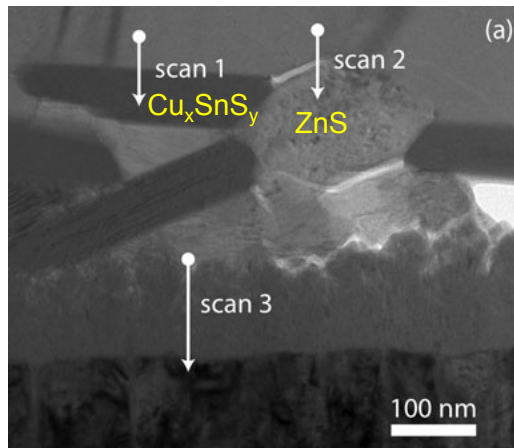


- ~220 nm MoSe₂ underneath TiN
- Some out-diffusion of Cu into MoSe₂ from CZTSe

Phase separation and interdiffusion

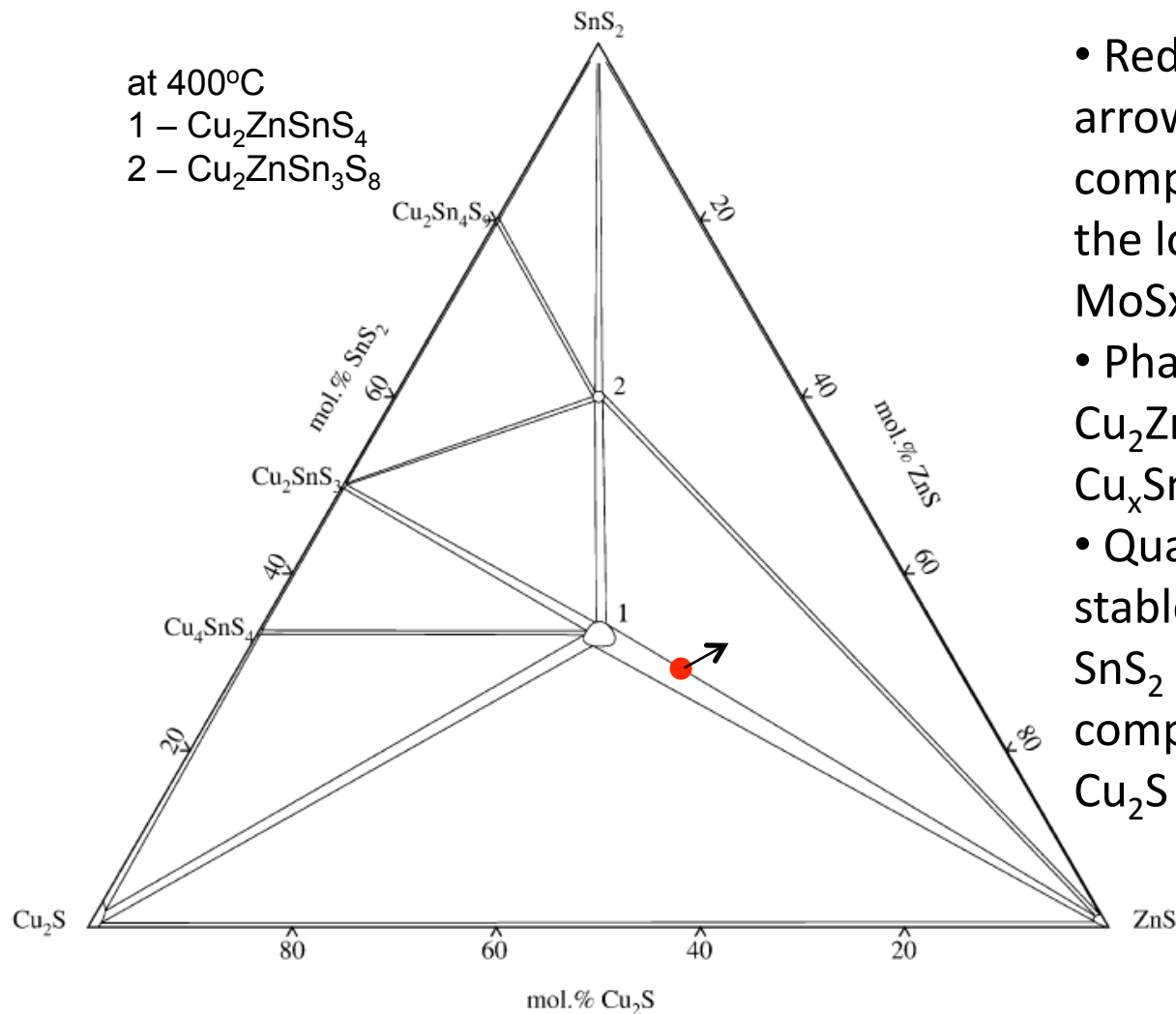


- Bimodal grain size distribution



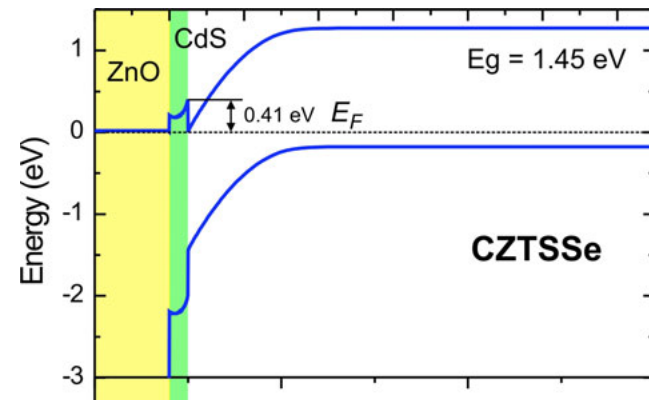
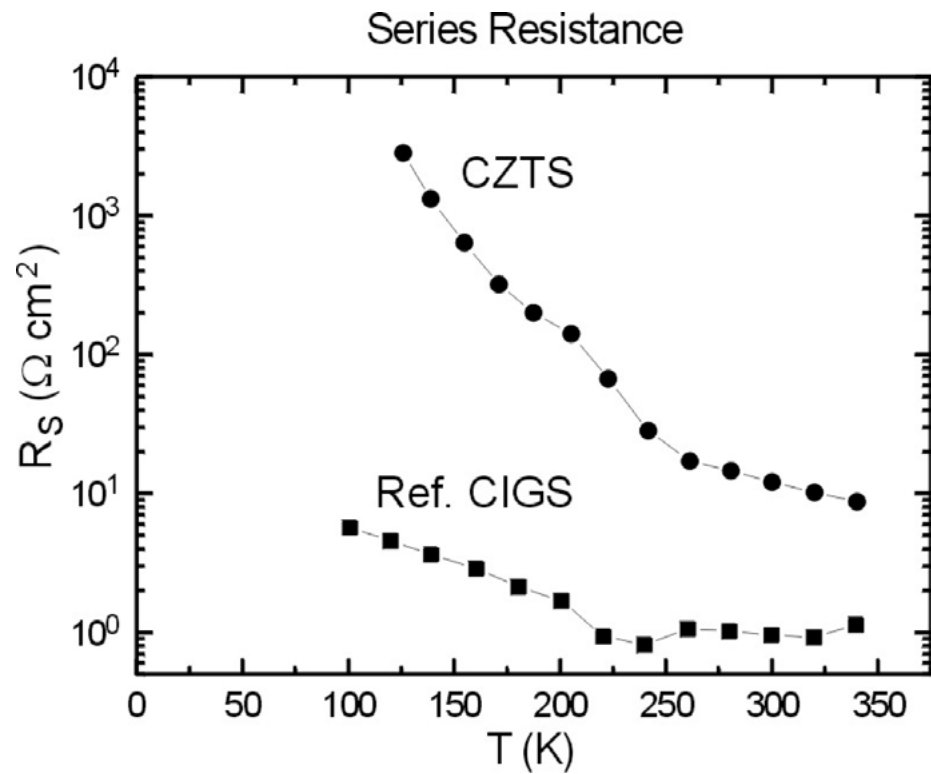
Observation:
 1) Phase separation of CZTS into ZnS and Cu_xSnS_y near back contact
 2) Cu diffuse in the MoS₂ amorphous layer

Microstructure issues increase with higher number of components



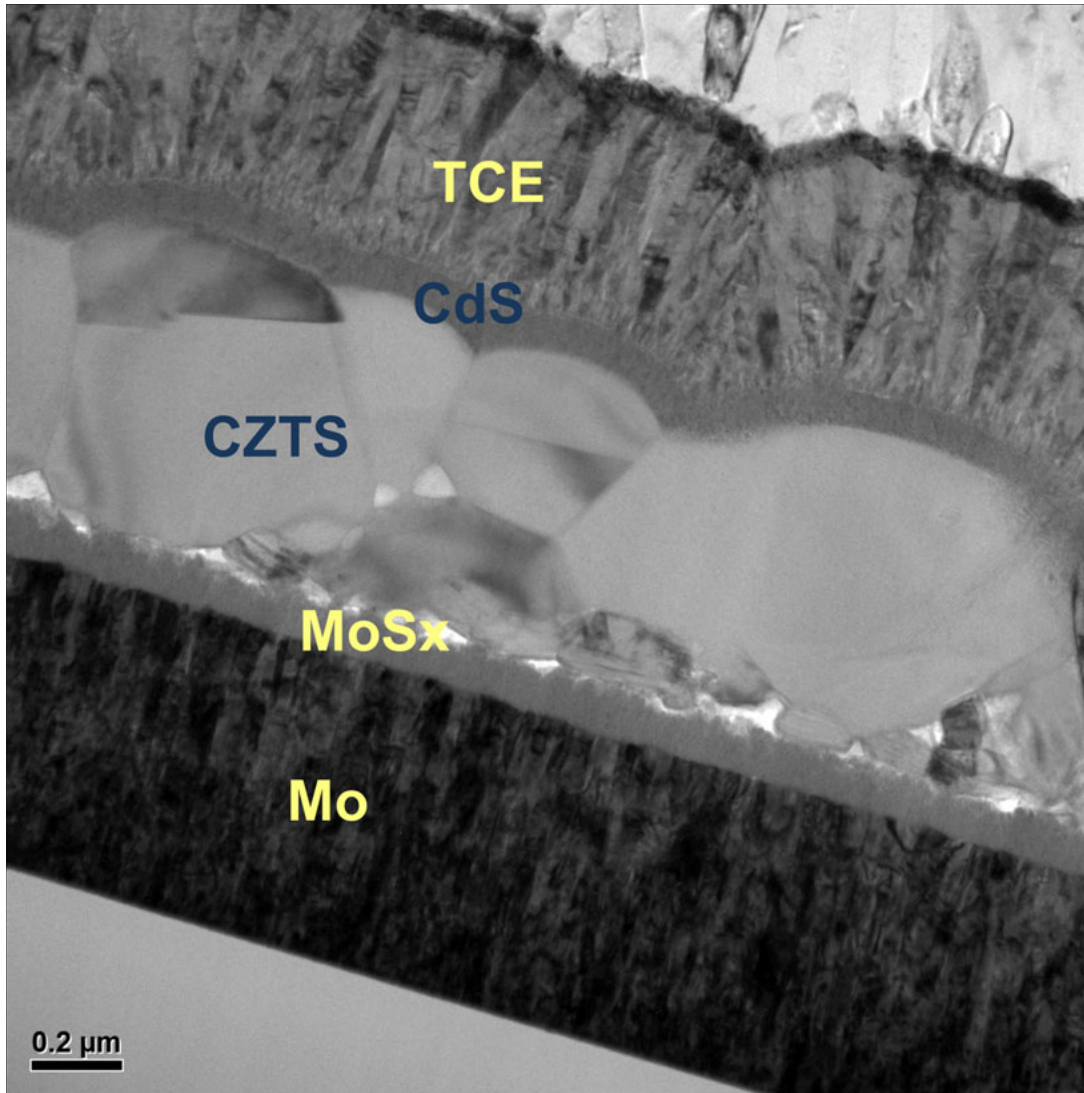
- Red dot: initial composition / arrow: direction of compositional change due to the loss of Cu from CZTS into MoS_x
- Phase diagram: $\text{CZTS} \Rightarrow \text{ZnS} + \text{Cu}_2\text{ZnSn}_3\text{S}_8$; TEM: $\text{CZTS} \Rightarrow \text{ZnS} + \text{Cu}_x\text{SnS}_y$
- Qualitative agreement: several stable solid solutions between SnS_2 and Cu_2S , while no stable compound between ZnS and Cu_2S or ZnS and SnS_2

Problem # 4: high series resistance



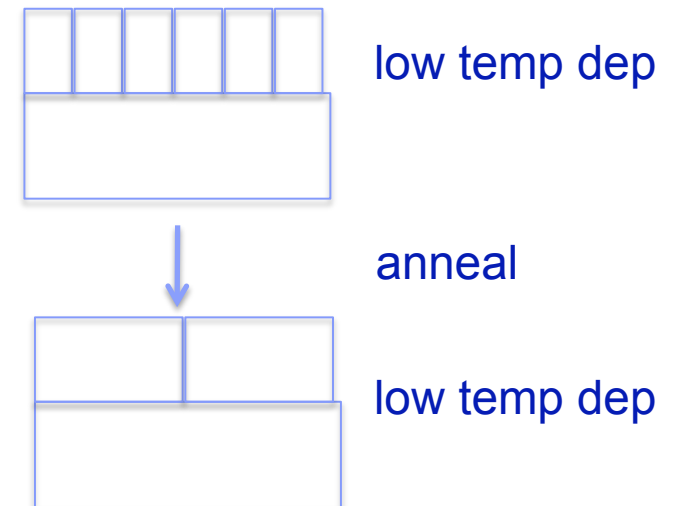
- Potential barriers
- Physical integrity of the interface

Problem # 5: Interfacial voiding and adhesion

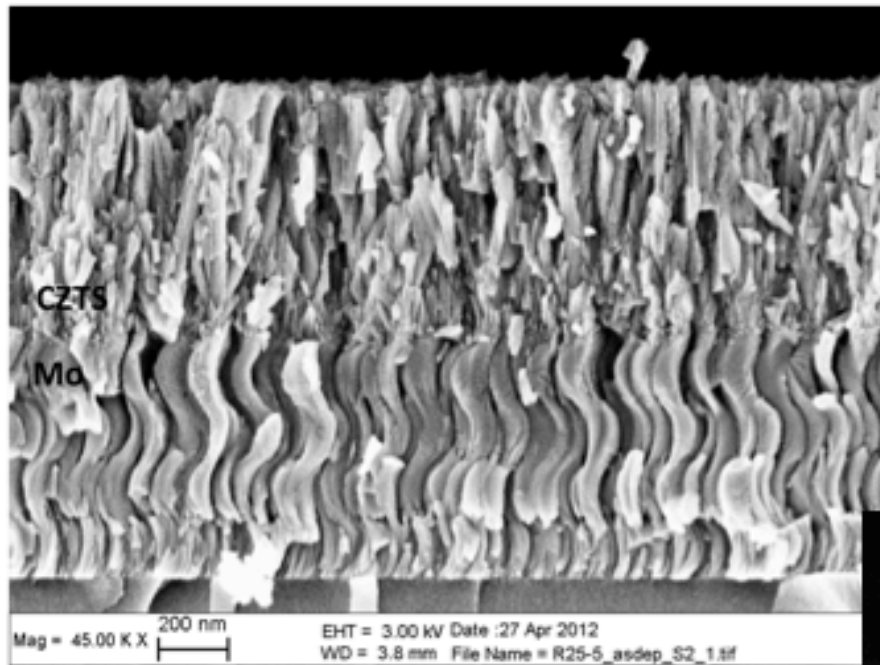


Interfacial energies—wetting layer

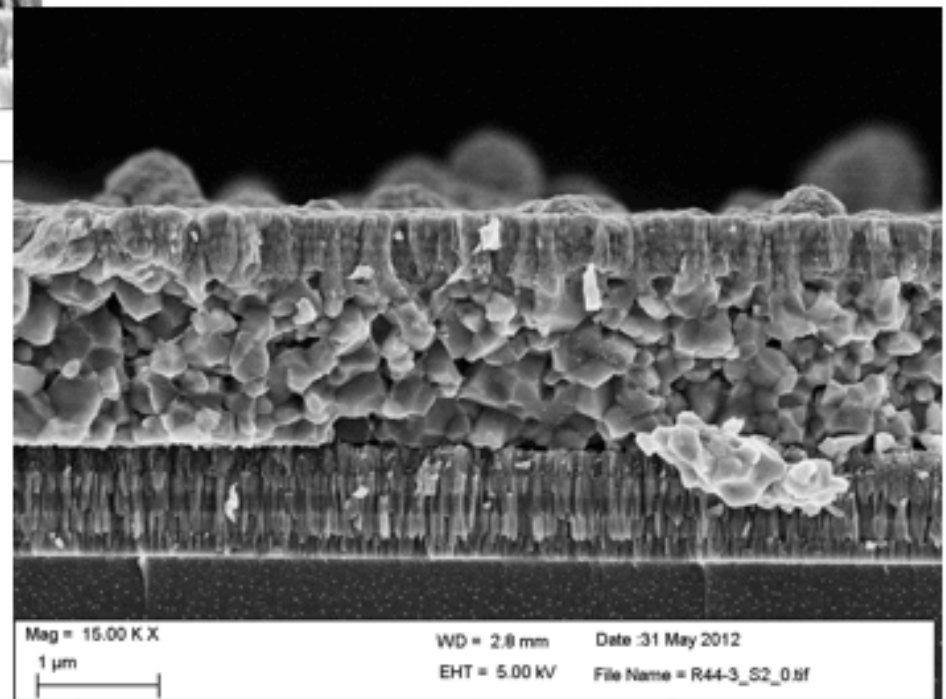
Voiding from gb growth and densification

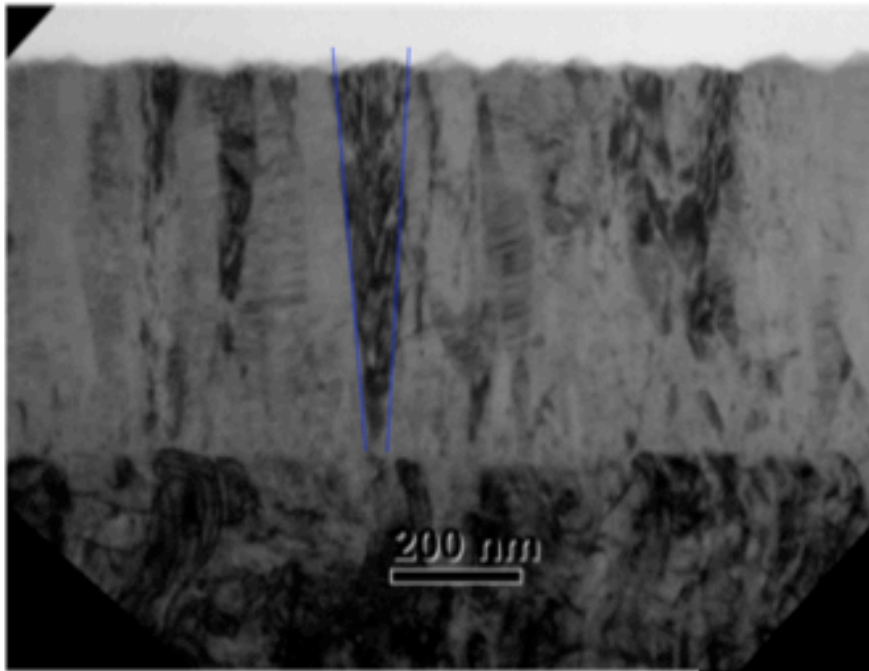


Grain growth

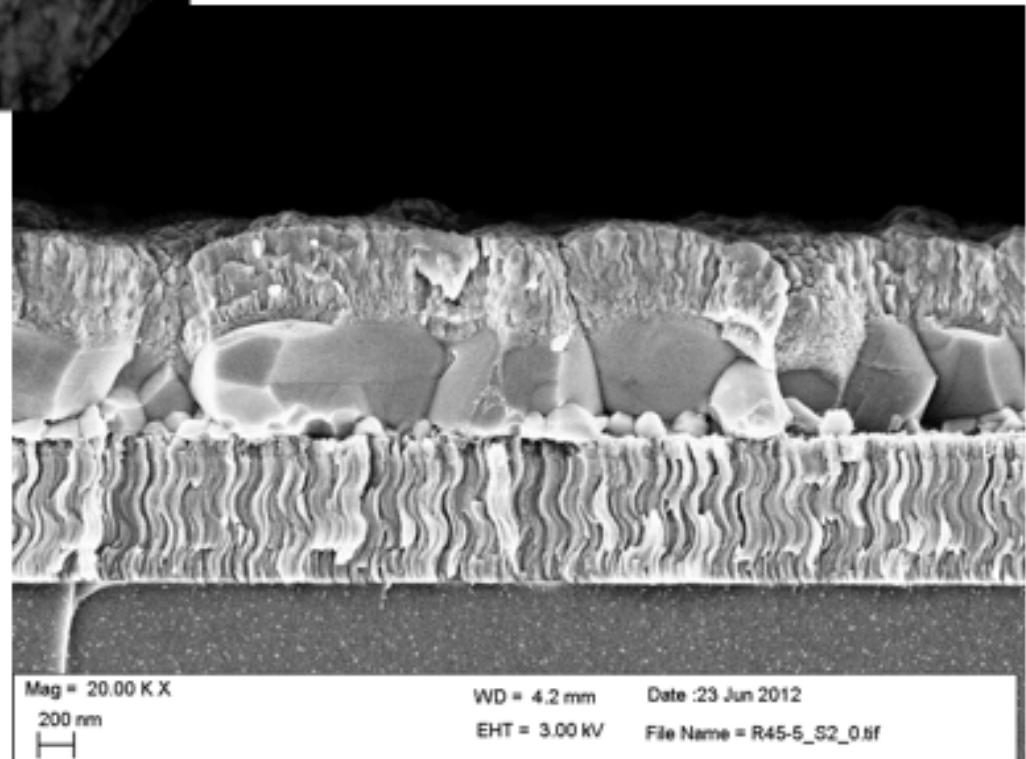


50 C deposition
580 C anneal





150 C deposition
580 C anneal



Challenge #6: New earth abundant materials

Absorber material	Band Gap(eV)	Device Structure	Highest efficiency	Remarks
Cu ₂ S	1.2	p Cu ₂ S/CdS	10-12%	Compound decomposes under own electric field, Cu ⁺⁺ ion motion; active work in early 80s.
FeS ₂	1		3%	Voc~200 mV; formation of other phases?
Zn ₃ P ₂	1.5	p Zn ₃ P ₂ /Mg/ITO	6%	6% reached in 1980*; Voc of 550 mV reached by Caltech group
Cu ₂ O	2	p Cu ₂ O/ZnO	3.80%**	formation of other phases? Exciton binding energy high
Mo & W sulfides and selenides	1-1.5		few %	

*Bhushan & Catalano, APL 1981

**Minami Appl Phys Express 2011

Things to do for earth abundant thin film solar cells

1. Modelling of the device with candidate bottom electrodes, emitters etc.
2. Role of the grain boundary
3. Phase and microstructure stability
4. New materials discovery